## 

# $0,80 \mathrm{~mm}$ HI-SP=ヨD SOCK=T HSEC8 SERIES 

## SPECIFIGATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8

Insulator Material:
Black Liquid
Crystal Polymer
Contact:
BeCu
Plating:
Au or Sn over $50 \mu^{\prime \prime}(1,27 \mu \mathrm{~m}) \mathrm{Ni}$ Current Rating:
$3.1 \mathrm{~A} @ 30^{\circ} \mathrm{C}$ Temperature Rise
Operating Temp:
$-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$
Card Insertion Depth:
(3,15mm).125" nominal
RoHS Compliant:
Yes

## Processing:

Max Processing Temp:
$230^{\circ} \mathrm{C}$ for 60 seconds, or $260^{\circ} \mathrm{C}$ for 20 seconds $3 x$ Lead-Free Solderable: Yes
SMT Lead Coplanarity: ( $0,10 \mathrm{~mm}$ ) .004" $\max (10-60)$

## STANDARD \& CUSTOM GARDS AVAILABLE

- Standard high speed interface cards for $19 \mathrm{~mm}, 25 \mathrm{~mm}$ \& 30 mm mated heights, singleended \& differential applications. See HSC8 Series.
- Cards for use with board locks
- Custom
 cards for low-cost stack height customization
- Samtec supplied card layout/artwork
to make your own cards
- Specialty card shapes


Note: Some lengths, styles and options are non-standard, non-returnable.

## Mates with:

$1,6 \mathrm{~mm}$ thick cards,


मIGH SPE=D CABLE $\&$ FLIEX APPLIGATIONS



Due to technical progress, all designs, specifications and components are subject to change without notice.

